



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: WP710A10ZGC/G

Green

Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life - solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

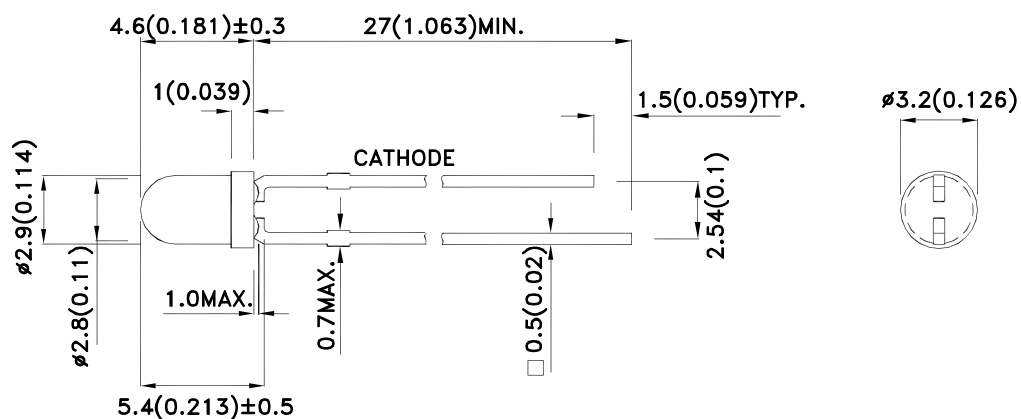
The Green source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP710A10ZGC/G	Green (InGaN)	WATER CLEAR	8000	14000	34°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Green	520		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	Green	525		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green	35		nm	I _F =20mA
C	Capacitance	Green	100		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Green	3.2	4	V	I _F =20mA
I _R	Reverse Current	Green		50	uA	V _R = 5V

Notes:

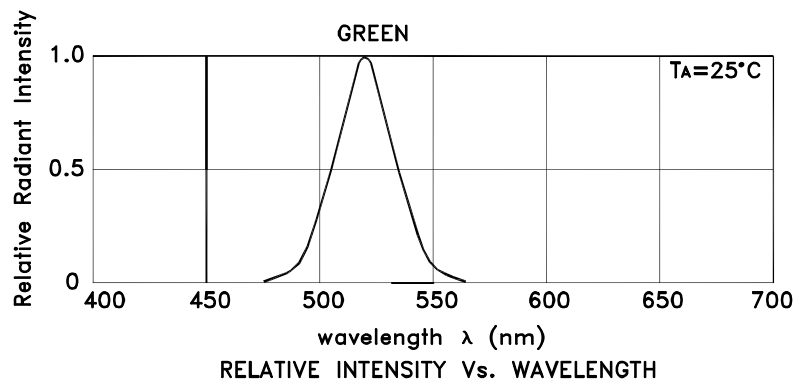
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	120	mW
DC Forward Current	30	mA
Peak Forward Current [1]	100	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

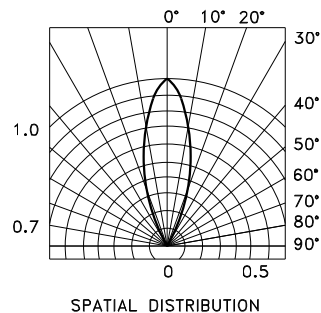
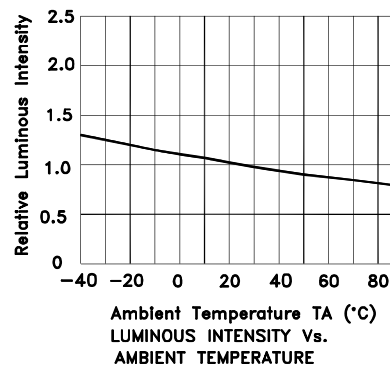
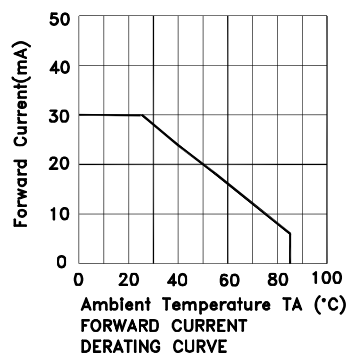
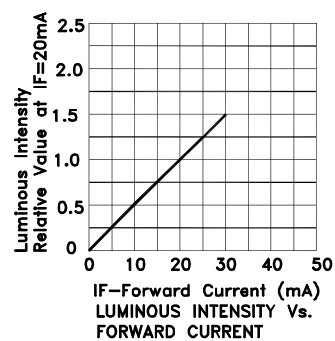
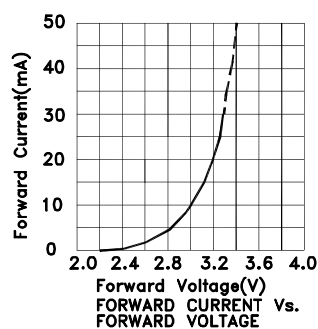
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



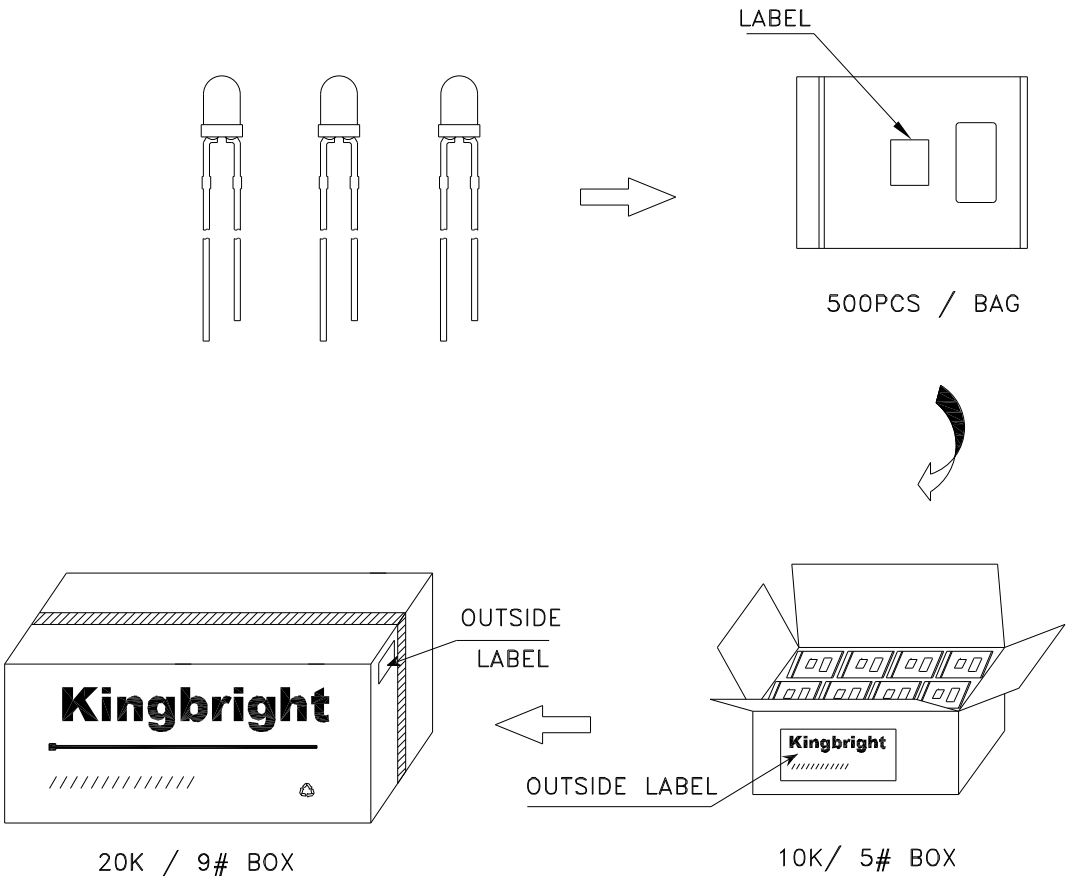
Green

WP710A10ZGC/G



PACKING & LABEL SPECIFICATIONS

WP710A10ZGC/G



Kingbright				
P/NO: WP710A10xxx				
QTY: 500 pcs	Q.C. <table border="1"><tr><td>Q C</td></tr><tr><td>XX XX XX</td></tr><tr><td>PASSED</td></tr></table>	Q C	XX XX XX	PASSED
Q C				
XX XX XX				
PASSED				
S/N: XXXX				
CODE: XXX				
LOT NO:				
 xxxxxxxxxxxxxxxxxxxxxxxx				
RoHS Compliant				

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



Fig.1

"○" Correct mounting method "×" Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

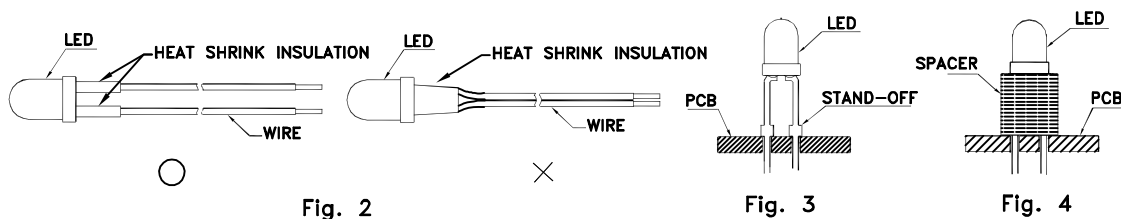


Fig. 2

Fig. 3

Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



Fig. 5



Fig. 6

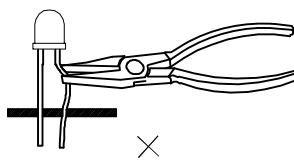


Fig. 7

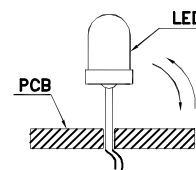


Fig. 8

7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

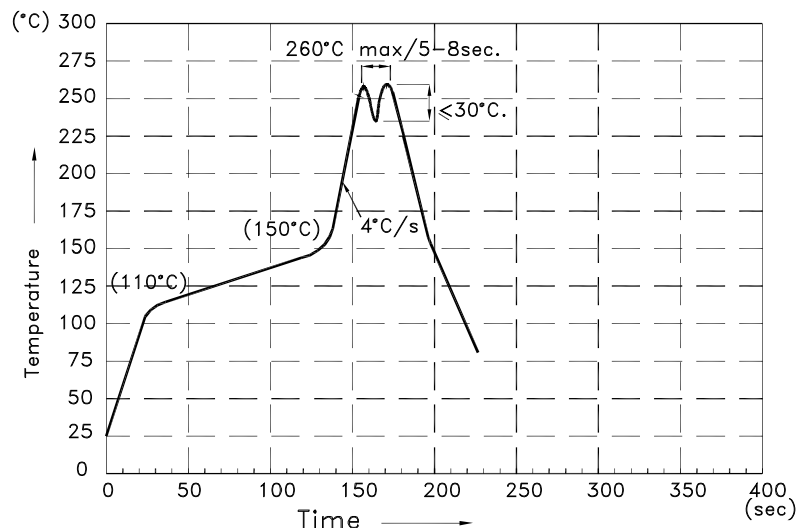


8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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